



XA-9890  
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Takashi MIWA et al.

Appln. No.: 10/606,891                          Group Art Unit: 2824

Filed: June 27, 2003                          Examiner: A. Tran

For: STACKED LARGE-SCALE INTEGRATED CIRCUIT (LSI)  
SEMICONDUCTOR DEVICE WITH MINIATURIZATION AND THINNING OF  
PACKAGE (AS AMENDED)

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AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
Sir:

In response to the non-final Office Action mailed on January 11, 2005, please amend the above-identified patent application as indicated below.

Amendments to the specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims, which begins on page 3 of this paper.

Amendments to the drawings begin on page 11 of this paper and include two replacement sheets.

Remarks begin on page 12 of this paper.